

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DB3X316J

Silicon epitaxial planar type

For small current rectification

■ Features

- Short reverse recovery time t_{rr}
- Low forward voltage V_F
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 5G

■ Basic Part Number

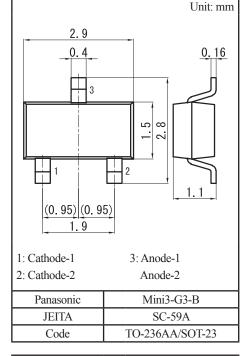
Dual DB2S316 (Common anode)

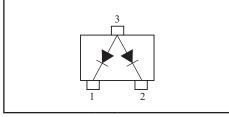
Packaging

DB3X316J0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit		
Reverse voltage		V_R	V _R 30		
Repetitive peak reverse voltage		V _{RRM}	30	V	
Forward current (Average)	Single		100	mA	
	Double *1	$I_{F(AV)}$	70		
Peak forward current	Single	т	300	mA	
	Double *1	I_{FM}	200		
Non-repetitive peak reverse surge voltage *2		I _{FSM}	1	A	
Junction temperature		T _j	125	°C	
Operating ambient temperature		T _{opr}	-40 to +85	°C	
Storage temperature		T _{stg}	-55 to +125	°C	





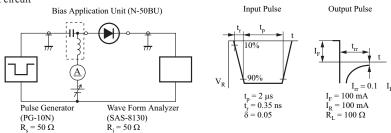
Note) *1: Value of each diode in double diodes used.

■ Electrical Characteristics $T_a = 25$ °C±3°C

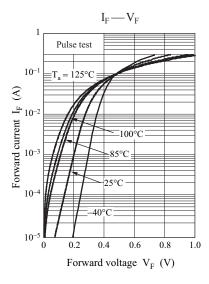
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			15	μΑ
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$		0.8		ns

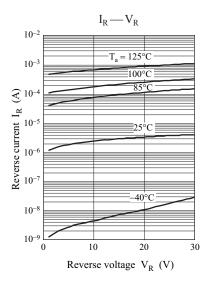
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

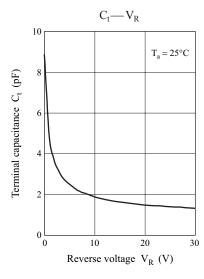
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
 - *1: t_{rr} measurement circuit



^{*2: 50} Hz sine wave 1 cycle (Non-repetitive peak current)



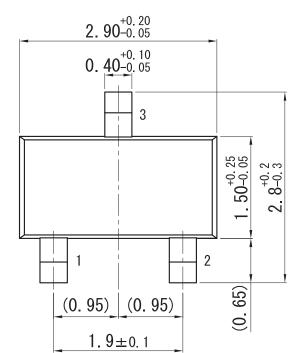


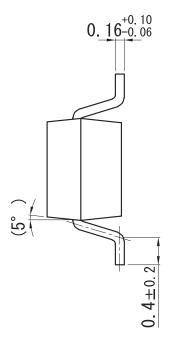


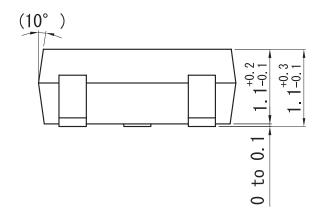
Ver. DED 2

Unit: mm

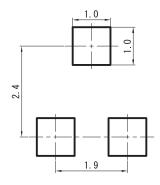
Mini3-G3-B







■ Land Pattern (Reference) (Unit: mm)



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